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Further confirmations awaited...

Organizing Committee:

Akanshu Sharma (Chair)

Amit H Varma (Co-Chair)

Dheeraj Waghmare

Deepak Suthar

Fasih Ur Rehman

Gaurav Chobe

Luis David Fernandez Vasquez

Prathyusha Malladi

Shivam Sharma

For information contact:

Mr. Luis David Fernandez Vasquez

Email- syscon@purdue.edu

Ms. Prathyusha Malladi

Email- syscon@purdue.edu

Website:

<https://eng.purdue.edu/CCE/SySCCon>

(Abstract portal link is available on the website)

Important Dates:

- Submission of Abstracts – 22 Oct 2025
- Acceptance of Abstracts – 31 Dec 2025
- Submission of Full Paper – 28 Feb 2026
- Acceptance of Full Paper – 30 Apr 2026



1st International Symposium on Steel to Concrete Connections

August 3rd - 5th, 2026

Organized by:

Bowen Laboratory,
Lyles School of Civil and
Construction Engineering

Purdue University,
West Lafayette, IN

Co-sponsored by



About the Symposium

SySCCon 2026 marks the inaugural edition of International Symposium on “Steel to Concrete Connections”. The symposium will be held at Purdue University, West Lafayette, Indiana, USA and is targeted to bring the expertise of various educational institutes, researchers and industries together and provide an excellent platform to discuss the advancements in the field of steel to concrete connections.

Main Conference Topics

The symposium primarily targets three major topics:

- **Anchorage** (fastenings) in concrete construction
- **Bond** between reinforcement and concrete
- Steel-concrete **composite construction**

For detailed sub-topics relevant for the symposium, visit our website

Background

While connections between steel and concrete are major components in reinforced concrete and composite construction, platforms such as conferences or symposiums specifically targeting these topics are rare.

SySCCon 2026 is a unique symposium that focuses on the specific problems related to steel-concrete connections, such as in the field of anchorages (fastenings), bond and composite construction. Past decades have seen significant advancements in these fields that include development of new products and materials, shift in design philosophies to performance-based approaches, newer construction methods, and incorporation of advanced tools such as detailed numerical modeling, machine learning etc. In research and practice.

The symposium will be equally useful for researchers, design engineers, product manufacturers, code and approval committee members and more.

Proceedings

All accepted papers will be published electronically as conference proceedings.

Registration Fees

Conference registration fees includes a welcome reception, coffee breaks, a conference banquet, attendance at all sessions and a copy of the conference proceedings.

Full delegate:	\$ 550 (Early bird)
Full delegate:	\$ 660 (Standard)
Students:	\$ 275 (Early bird)
Students:	\$ 330 (Standard)

Accompanying person*: \$ 120

*The accompanying person registration includes the welcome reception and symposium banquet. Options of guided tours will be provided at additional costs.

Call for Sponsorship

Use this opportunity to sponsor the event and showcase your expertise and innovative products at the conference. Please visit our website or email us to learn more about the sponsorship options.

